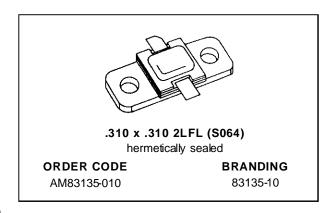


### AM83135-010

# RF & MICROWAVE TRANSISTORS S-BAND RADAR APPLICATIONS

- REFRACTORY/GOLD METALLIZATION
- EMITTER SITE BALLASTED
- LOW THERMAL RESISTANCE
- INPUT/OUTPUT MATCHING
- OVERLAY GEOMETRY
- METAL/CERAMIC HERMETIC PACKAGE
- P<sub>OUT</sub> = 10 W MIN. WITH 5.0 dB GAIN



### DESCRIPTION

The AM83135-010 device is a high power silicon bipolar NPN transistor specifically designed for S-Band radar pulsed output and driver applications.

This device is characterized at  $100\mu$ sec pulse width and 10% duty cycle, but is capable of operation over a range of pulse widths, duty cycles, and temperatures, and can withstand a 3:1 output VSWR with a + 1 dB input overdrive. Low RF thermal resistance, refractory/gold metallization, and computerized automatic wire bonding techniques ensure high reliability and product consistency (including phase characteristics).

The AM83135-010 is supplied in the IMPAC™ hermetic metal/ceramic package with internal input/output impedance matching circuitry, and is intended for military and other high reliability applications.

# PIN CONNECTION 1. Collector 3. Emitter 2. Base 4. Base

### **ABSOLUTE MAXIMUM RATINGS** $(T_{case} = 25^{\circ}C)$

Symbol	Parameter	Value	Unit
Poiss	Power Dissipation* (T <sub>C</sub> ≤ 50°C)	50	W
Ic	Device Current*	А	
Vcc	Collector-Supply Voltage*	46	V
TJ	Junction Temperature (Pulsed RF Operation)	250	°C
T <sub>STG</sub>	Storage Temperature	- 65 to +200	°C

### THERMAL DATA

R <sub>TH(j-c)</sub>	Junction-Case Thermal Resistance*	4.0	°C/W

<sup>\*</sup>Applies only to rated RF amplifier operation

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### **ELECTRICAL SPECIFICATIONS** (T<sub>case</sub> = 25°C)

### STATIC

Symbol	Test Conditions	Value			11:4		
		Min.	Тур.	Max.	Unit		
BV <sub>CBO</sub>	I <sub>C</sub> = 7 mA	$I_E = 0 \text{ mA}$		55	_		V
BV <sub>EBO</sub>	I <sub>E</sub> = 1 mA	$I_C = 0 \text{ mA}$		3.5	_	_	V
BVcer	I <sub>C</sub> = 7 mA	$R_{BE} = 10 \Omega$		55	_	_	V
ICES	V <sub>BE</sub> = 0 V	$V_{CE} = 40 \text{ V}$		_	_	5	mA
h <sub>FE</sub>	V <sub>CE</sub> = 5 V	I <sub>C</sub> = 600 mA		30	_	_	_

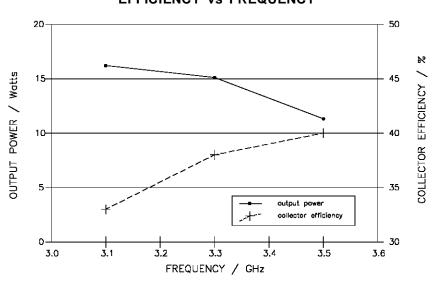
### **DYNAMIC**

Symbol	Took Conditions		Value		IIm:4		
Symbol	Test Conditions			Min.	Тур.	Max.	Unit
Pout	f = 3.1 – 3.5 GHz	$P_{IN} = 3.2 \text{ W}$	$V_{CC} = 40 V$	10	_	_	W
ης	f = 3.1 – 3.5 GHz	$P_{OUT} = 10 \text{ W}$	$V_{CC} = 40 \text{ V}$	30	_	_	%
P <sub>G</sub>	f = 3.1 – 3.5 GHz	P <sub>OUT</sub> = 10 W	$V_{CC} = 40 \text{ V}$	5.0	_	_	dB

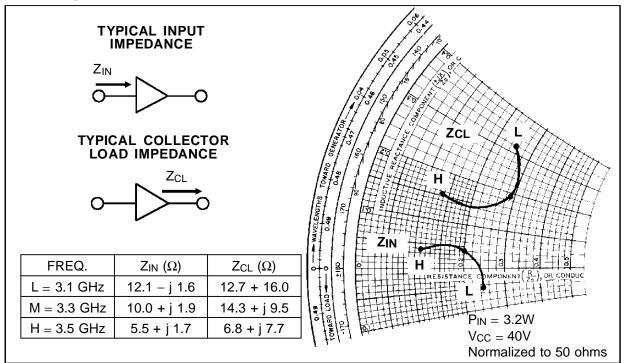
Note: Pulse Width =  $100\mu$ Sec Duty Cycle = 10%

### TYPICAL PERFORMANCE

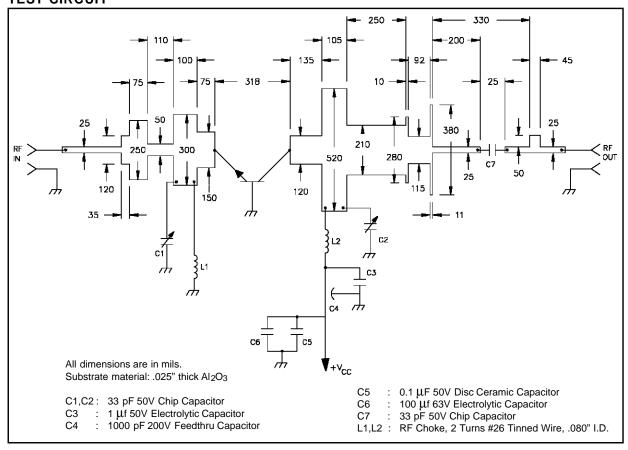
## POWER OUTPUT & COLLECTOR EFFICIENCY vs FREQUENCY



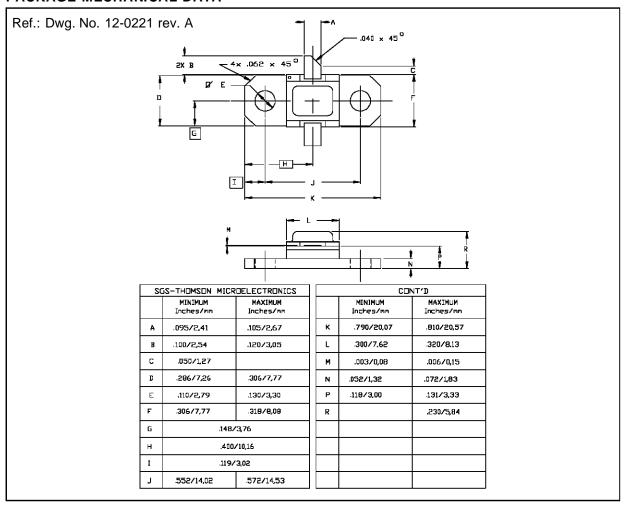
### **IMPEDANCE DATA**



### **TEST CIRCUIT**



### PACKAGE MECHANICAL DATA



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